IDAHO SOCIETY OF PROFESSIONAL LAND SURVEYORS

Graduating High School Senior

Scholarship Application

PO Box 7886
Boise, ID 83707
(208) 658-9970

www.idahospls.org

ELIGIBLE STUDENTS: Applicants must be graduating seniors from an Idaho high school who will be enrolling in the Surveying and Geomatics Engineering Technology or Civil Engineering Technology at an Idaho College or University as a full-time student (defined as 12 credit hours) for the fall semester. Applicants must have a minimum 2.0 GPA from an accredited Idaho high school.

RETURN APPLICATION TO: Idaho Society of Professional Land Surveyors, PO Box 7886, Boise, ID 83707 or scan and email to tottens@amsidaho.com no later than the 5:00pm on the day of the deadline.

APPLICATION DEADLINE: April 1, 2019

First Name ______________________ Middle ______________________Last _______________________

Mailing Address ____

Phone Number __________________________ Email Address ____________________________________

High School and Location____

College or University Program you intend to enroll in ____

WRITTEN STATEMENT: Attach a written statement (500 words) addressing your educational and career goals, your plans to finance your education and why you are deserving of this scholarship.

LETTERS OF RECCOMENDATION: Attach two letters of recommendation from a high school teacher, guidance counselor, or employer.

TRANSCRIPTS: Include with this application a copy of your most recent high school transcripts (unofficial is acceptable).

CERTIFICATION: I plan to enroll as a full-time student in the Surveying and Geomatics Engineering Technology or Civil Engineering Technology program at an Idaho College or University, beginning in the fall semester. If I receive one of the ISPLS scholarships, I understand that the funds will be paid directly to the College or University for distribution to my account in two parts: $250 when I register for the fall semester and the remaining $250 when I have completed the fall semester with a GPA of at least 3.0 and have registered for the spring semester. If selected to receive a scholarship, I give permission for a publicity release.

Signature of Applicant ____ Date _________________